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| Nota di contenuto | Design of Micro Products Application of a DF?A Methodology to facilitate the assembly of a Micro/Nano Measurement Device A DFA Framework for Hybrid Microsystems Statistical Assemblies with form Errors — A 2D Example A Classification and Coding System for Micro-Assembly A Method for Three Dimensional Tolerance Analysis and Synthesis Applied to Complex and Precise Assemblies New Designs for Submillimetric Press-Fitting Design and Testing of an Ortho-Planar Micro-Valve Robust Design of a Lens System of Variable Refraction Power with Respect to the Assembly Process Micro-Assembly Processes and Applications Product-Process Ontology for Managing Assembly Specific Knowledge Between Product Design and Assembly System Simulation Bridging the Gap — from Process Related Documentation to an Integrated Process and Application Knowledge Management in Micro Systems Technology Distributed Simulation in Manufacturing Using High Level Architecture Adaptive Packaging Solution for a Microlens Array Placed Over a Micro-UV-LED Array Solder Bumping — A Flexible Joining Approach for the Precision Assembly of Optoelectronical Systems Fluidassem - A New Method of Fluidic-Based Assembly with Surface Tension Concepts for Hybrid Micro Assembly Using Hot Melt Joining |

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